

Vacuum Ovens

DP63C-T75

Usage: Processing special materials in the industry.

- Single chamber structure, heating through copper plate, fully-automatic control of vacuum and gas intake.
- Equipped with a high-speed vortex vacuum pump to rapidly reduce pressure, in conjunction with a precision molecular pump to achieve a high vacuum environment.
- Water cooling system: Protects the molecular pump and pneumatic flap valve, connects the internal hot plate, allowing for rapid temperature reduction in the chamber after heating is completed.
- Equipped with a high vacuum manual flap valve for manual vacuum breaking.

Specifications

Product name	Vacuum Ovens DP63C-T75
Pressure range	101kPa-1X10 ⁻² Pa
Pressure drop time	≤60min (101kPa-0.01Pa)
Pressure recovery time	≤2min (0.01Pa-101kPa)
Operating temperature range	40°C ~ 400°C
Internal chamber dimensions	W450×D450×H450 (effective height between heating plates 3×130)
External dimensions	W1090×D1380×H1890 (excluding protrusions, excluding vacuum pump)



Forced convection

Natural convection

Fine

Options

For labware

Explosion-proof

Far infrared heating

Anaerobic

Clean

Vacuum

Semiconductor & electronics

Battery

Flat panel display

Others

Cart-type Constant Temp. Ovens

YJ150901

Usage: Heat treatment of bathroom building materials.

- Exhaust air volume manually adjustable.
- A ramp is set at the door for easy access by the cart frame.
- Configured with cart and sample frame.

Specifications

Product name	Cart-type Constant Temperature Ovens YJ150901
Temp. control range	Room temp. +15 ~ 200°C
Heating time	Room temperature ~ 200°C approximately 60min (no load & exhaust port fully closed)
Temp. adjusting accuracy	±1.0°C (at 200°C no load & exhaust port fully closed)
Temp. distribution accuracy	±2.5°C (at 200°C no load & exhaust port fully closed)
External dimensions	W900×D1290×H1630 (excluding protrusions)

